

# PTF 10112

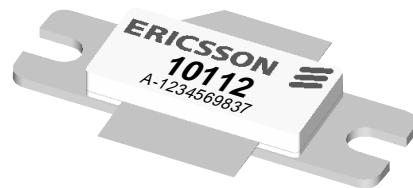
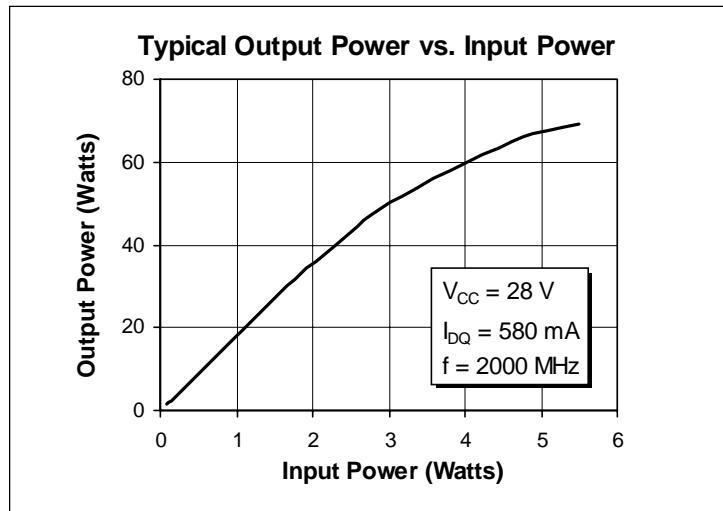
## 60 Watts, 1.8–2.0 GHz

### GOLDMOS™ Field Effect Transistor

#### Description

The PTF 10112 is an internally matched common source N-channel enhancement-mode lateral MOSFET intended for CDMA and TDMA applications from 1.8 to 2.0 GHz. It is rated at 60 watts power output. Nitride surface passivation and full gold metallization ensure excellent device lifetime and reliability.

- **INTERNALLY MATCHED**
- Guaranteed Performance at 1.93, 1.99 GHz, 28 V
  - Output Power = 60 Watts Min
  - Power Gain = 12 dB Typ
- Full Gold Metallization
- Silicon Nitride Passivated
- Back Side Common Source
- Excellent Thermal Stability
- 100% Lot Traceability



Package 20248

#### RF Specifications (100% Tested)

Characteristic	Symbol	Min	Typ	Max	Units
<b>Gain</b> ( $V_{DD} = 28$ V, $P_{OUT} = 15$ W, $I_{DQ} = 580$ mA, $f = 1.93, 1.99$ GHz)	$G_{ps}$	11	12	—	dB
<b>Power Output at 1 dB Compression</b> ( $V_{DD} = 28$ V, $I_{DQ} = 580$ mA, $f = 1.99$ GHz)	$P_{-1dB}$	60	—	—	Watts
<b>Drain Efficiency</b> ( $V_{DD} = 28$ V, $P_{OUT} = 60$ W, $I_{DQ} = 580$ mA, $f = 1.99$ GHz)	$\eta_D$	—	41	—	%
<b>Load Mismatch Tolerance</b> ( $V_{DD} = 28$ V, $P_{OUT} = 60$ W, $I_{DQ} = 580$ mA, $f = 1.99$ GHz —all phase angles at frequency of test)	$\Psi$	—	—	10:1	—

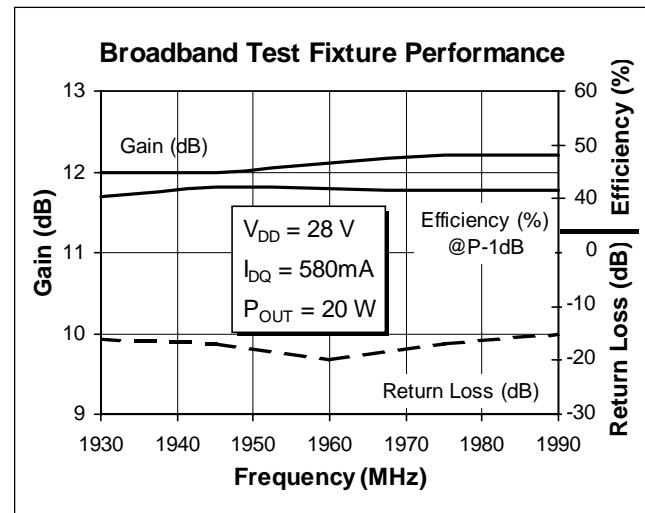
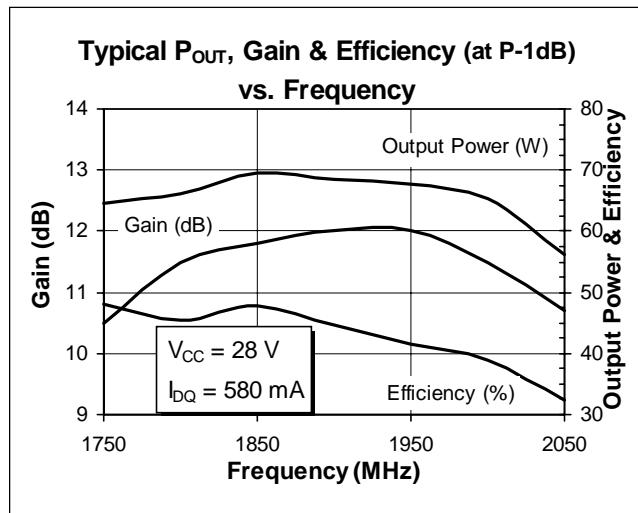
All published data at  $T_{CASE} = 25^\circ\text{C}$  unless otherwise indicated.

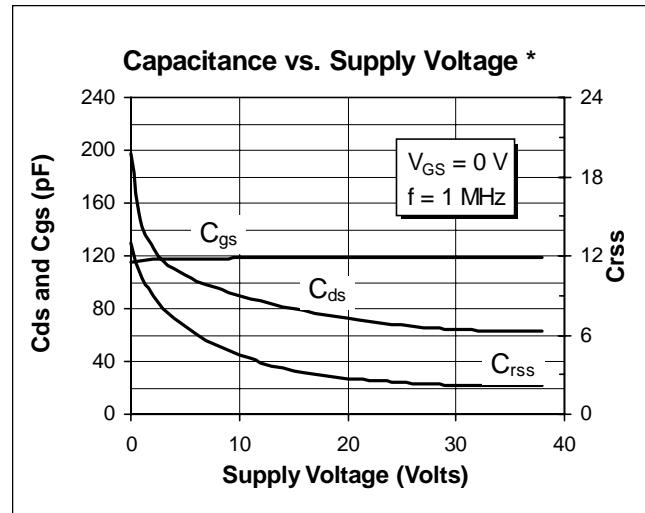
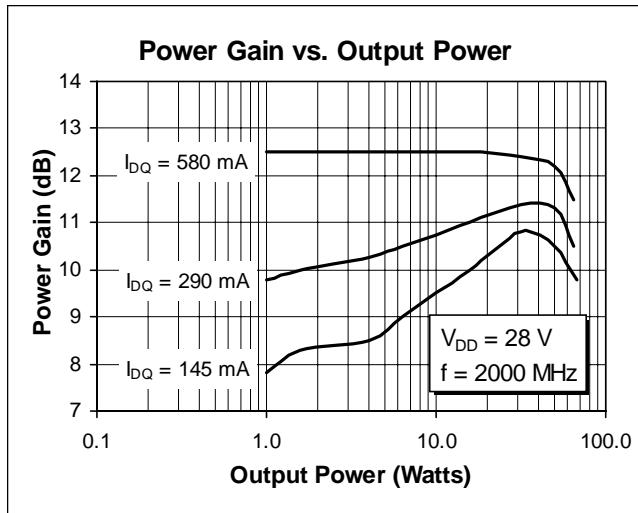
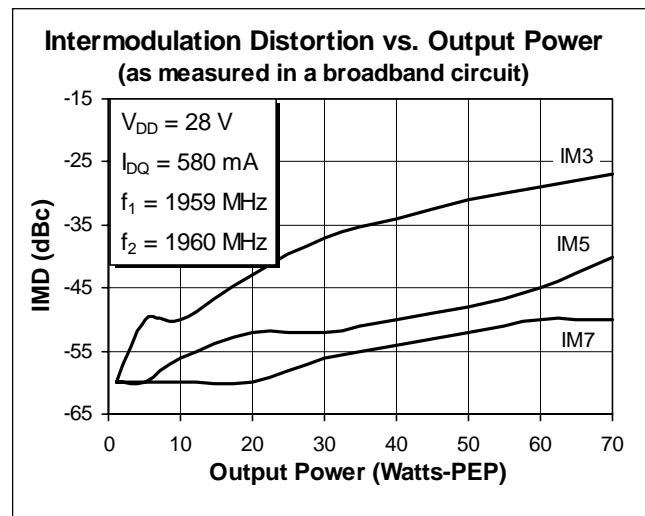
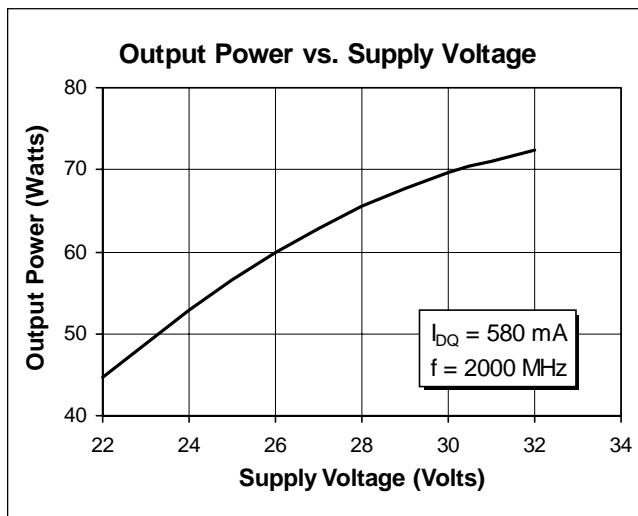
**Electrical Characteristics** (100% Tested)

Characteristic	Conditions	Symbol	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ , $I_D = 100 \text{ mA}$	$V_{(BR)DSS}$	65	—	—	Volts
Zero Gate Voltage Drain Current	$V_{DS} = 28 \text{ V}$ , $V_{GS} = 0 \text{ V}$	$I_{DSS}$	—	—	5.0	mA
Gate Threshold Voltage	$V_{DS} = 10 \text{ V}$ , $I_D = 150 \text{ mA}$	$V_{GS(\text{th})}$	3.0	—	5.0	Volts
Forward Transconductance	$V_{DS} = 10 \text{ V}$ , $I_D = 2 \text{ A}$	$g_{fs}$	—	4.0	—	Siemens

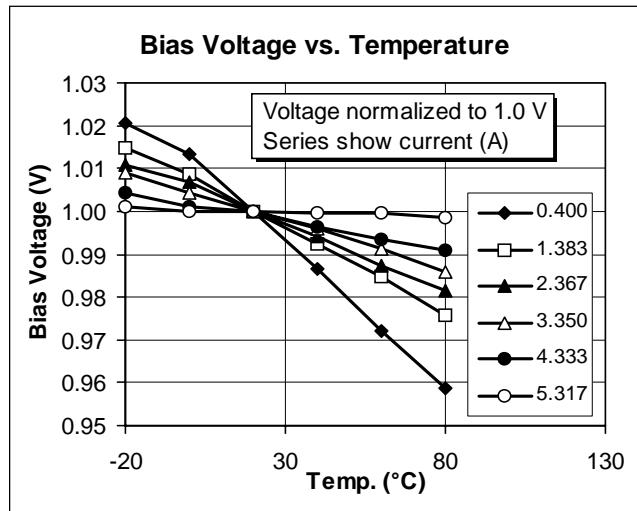
**Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	65	Vdc
Gate-Source Voltage	$V_{GS}$	$\pm 20$	Vdc
Operating Junction Temperature	$T_J$	200	°C
Total Device Dissipation at Above 25°C derate by	$P_D$	237	Watts
		1.35	W/°C
Storage Temperature Range	$T_{STG}$	-40 to +150	°C
Thermal Resistance ( $T_{CASE} = 70^\circ\text{C}$ )	$R_{\theta JC}$	0.74	°C/W

**Typical Performance**



\* This part is internally matched. Measurements of the finished product will not yield these results.

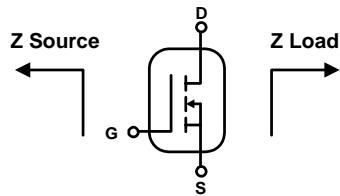


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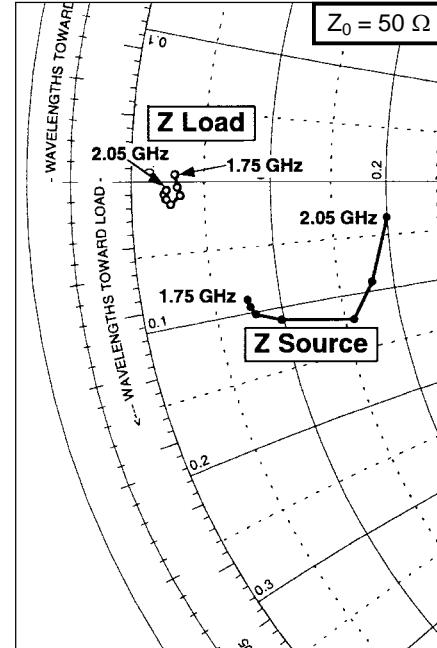
**ERICSSON** 

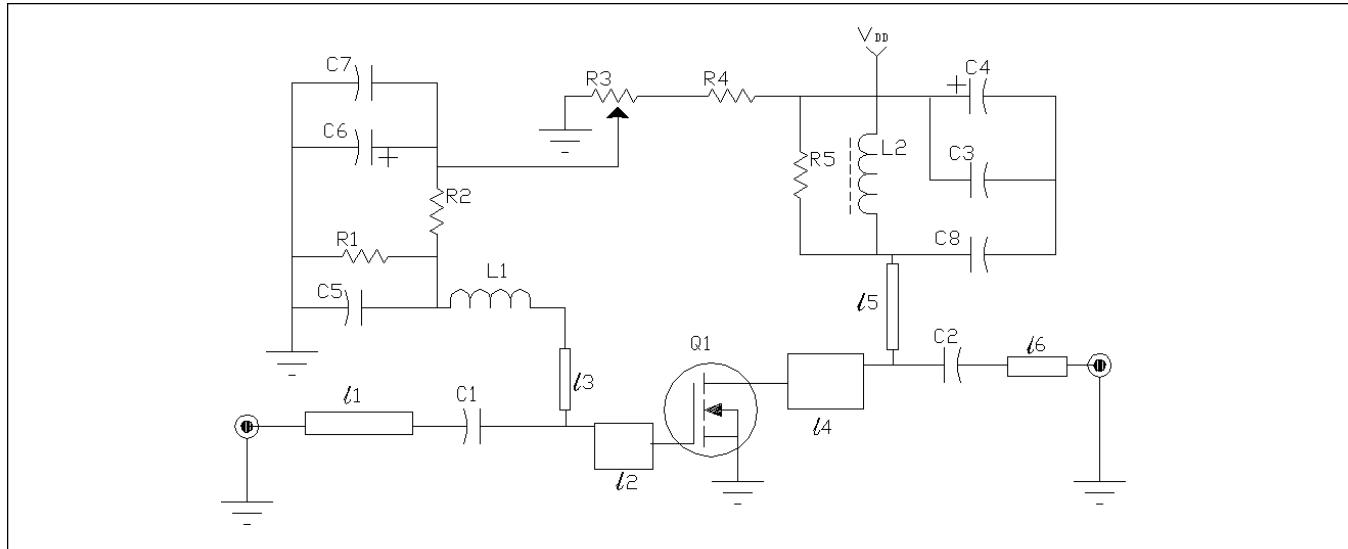
## Impedance Data

V<sub>DD</sub> = 28 V, P<sub>OUT</sub> = 60 W, I<sub>DQ</sub> = 580 mA

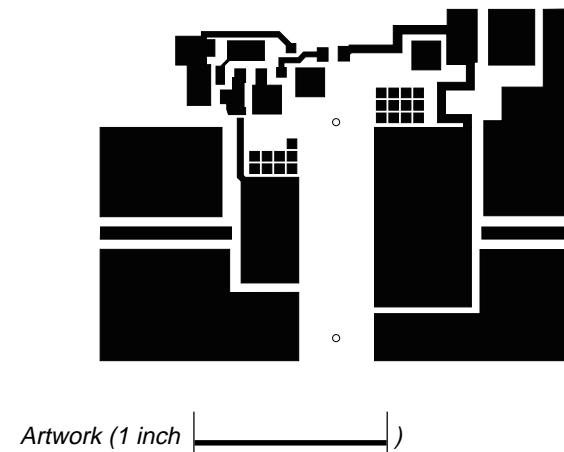
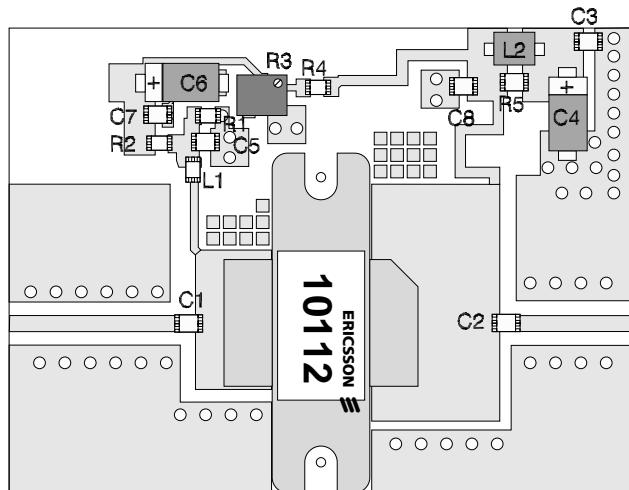


Frequency GHz	Z Source Ω		Z Load Ω	
	R	jX	R	jX
1.75	3.74	-4.50	1.48	0.25
1.80	3.80	-4.80	1.56	-0.20
1.85	3.96	-5.10	1.66	-0.50
1.90	4.90	-5.50	1.32	-0.80
1.95	7.90	-6.10	1.16	-0.60
2.00	9.00	-4.60	1.10	-0.45
2.05	10.00	-1.70	1.18	-0.30



**Test Circuit**

*Test Circuit Block Diagram for  $f = 1.93\text{--}1.99 \text{ GHz}$* 

Q1	PTF 10112	LDMOS RF Transistor	L1	2.7 nh	SMT Coil
$\ell_1, \ell_6$		Microstrip 50 $\Omega$	L2	4mm	SMT Ferrite Bead
$\ell_2$	.10 $\lambda$ @ 2.0 GHz	Microstrip 9.4 $\Omega$	R1, R2	220 $\Omega$	Chip Resistor K1206
$\ell_3$	.08 $\lambda$ @ 2.0 GHz	Microstrip 70 $\Omega$	R3	2K	SMT Potentiometer
$\ell_4$	.162 $\lambda$ @ 2.0 GHz	Microstrip 5.8 $\Omega$	R4	10 $\Omega$	Chip Resistor K1206
$\ell_5$	.22 $\lambda$ @ 2 GHz	Microstrip 65 $\Omega$	R5	1 $\Omega$	Chip Resistor K1206
C1, C2, C5, C8	10 pF Chip Cap	ATC 100 B	Circuit Board	.028" Dielectric Thickness, $\epsilon_r = 4.0$ , AlliedSignal, G200, 2 oz. copper	
C3, C7	0.1 $\mu\text{F}$ Chip Cap				
C4, C6	10 $\mu\text{F}$ SMT Tantalum				


*Parts Layout (not to scale)*

**Notes:**